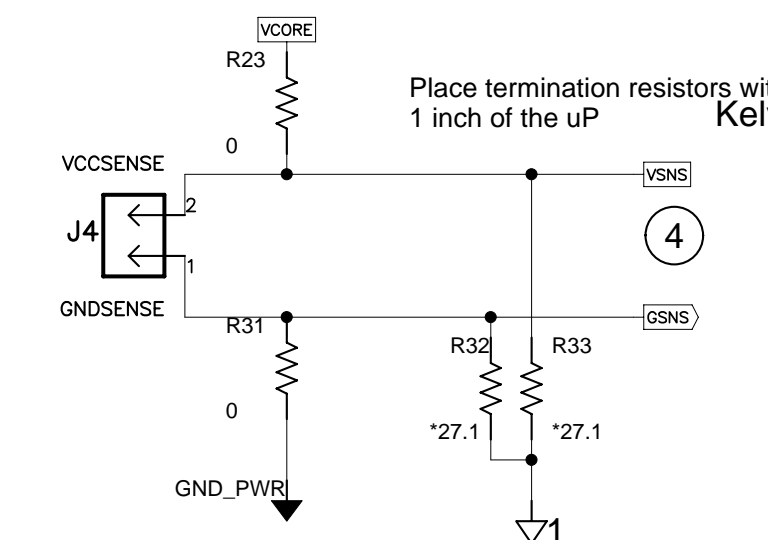
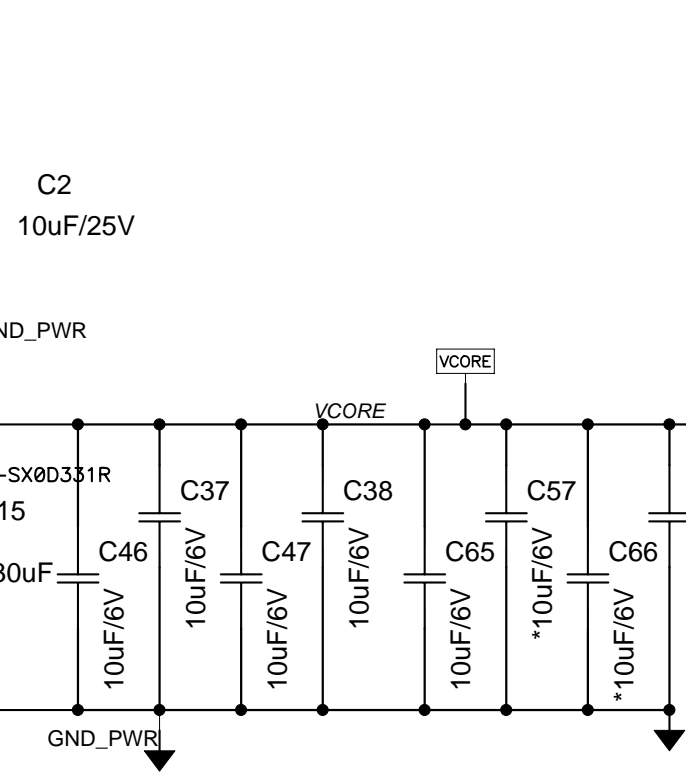


Differential Feedback Termination and Filtering



Current Feedback Selection and Filtering



R10 updated from 12.1 ohms to zero in test

② Kelvins from L1 diff. pair to R21 & R22

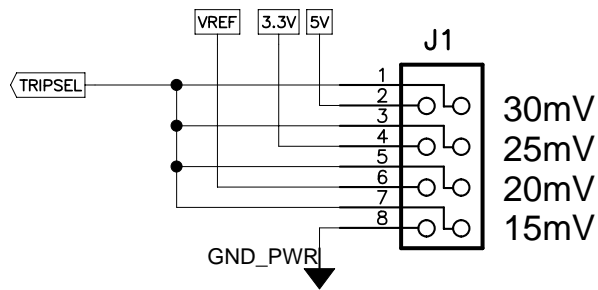
③ Kelvins from R8 diff. pair to R19 & R24

See Test Report which focused upon Thermals, main waveform and ripple out

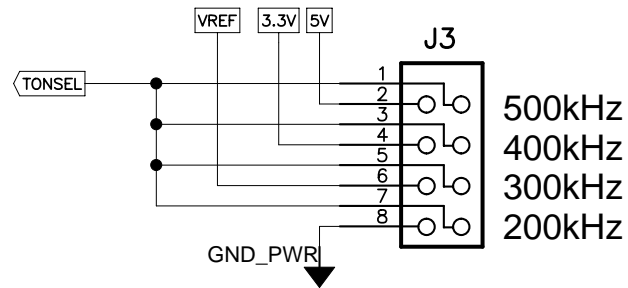
- Notes:
- ⚠ A "*" before a component value indicates this component is not populated in the standard configuration.
 - ② Kelvin connections from L1 to be run as differential pair to R19 & R24.
 - ③ Kelvin connections from R8 to be run as differential pair to R21 & R22.

Title			TPS51610/TPS51610I EVM w/CSD86330Q3D		
Size	Number	Rev		A	
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Filename	PMP5486_revA.sch	Sheet	1	of	3

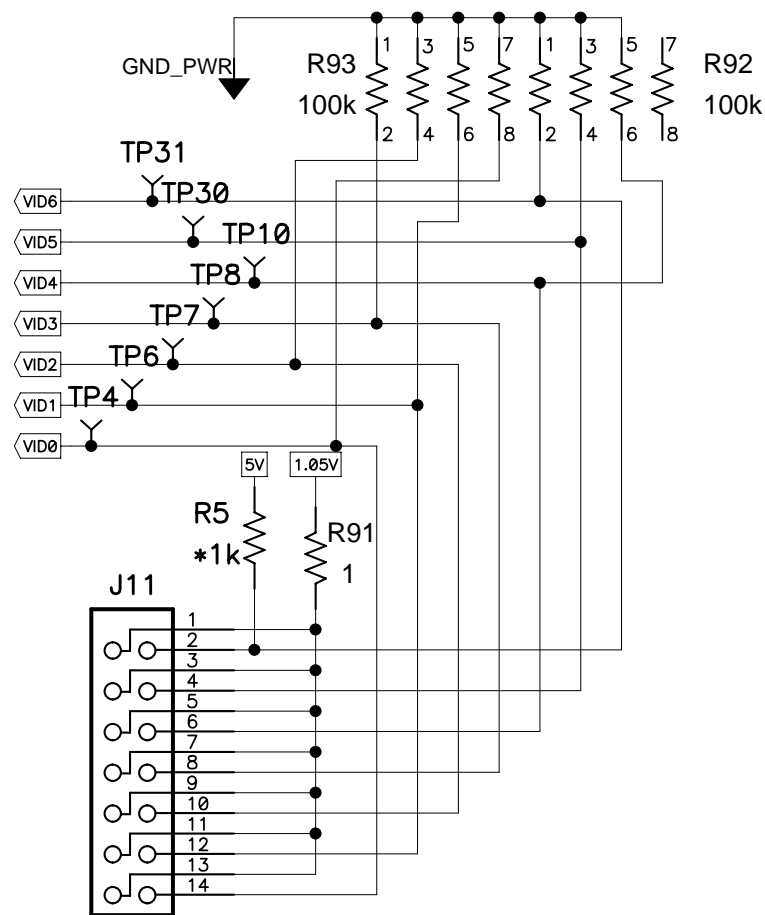
TRIPSEL 1 of 4 Selection Header



TONSEL 1 of 4 Selection Header

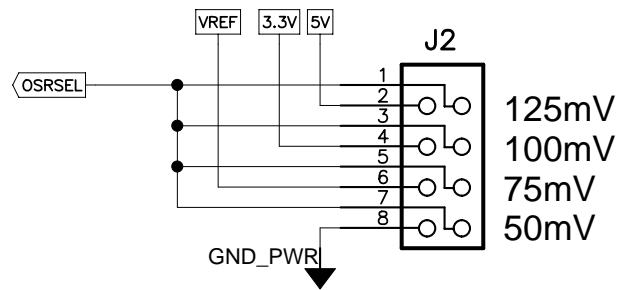


CPU mode, DNP R5

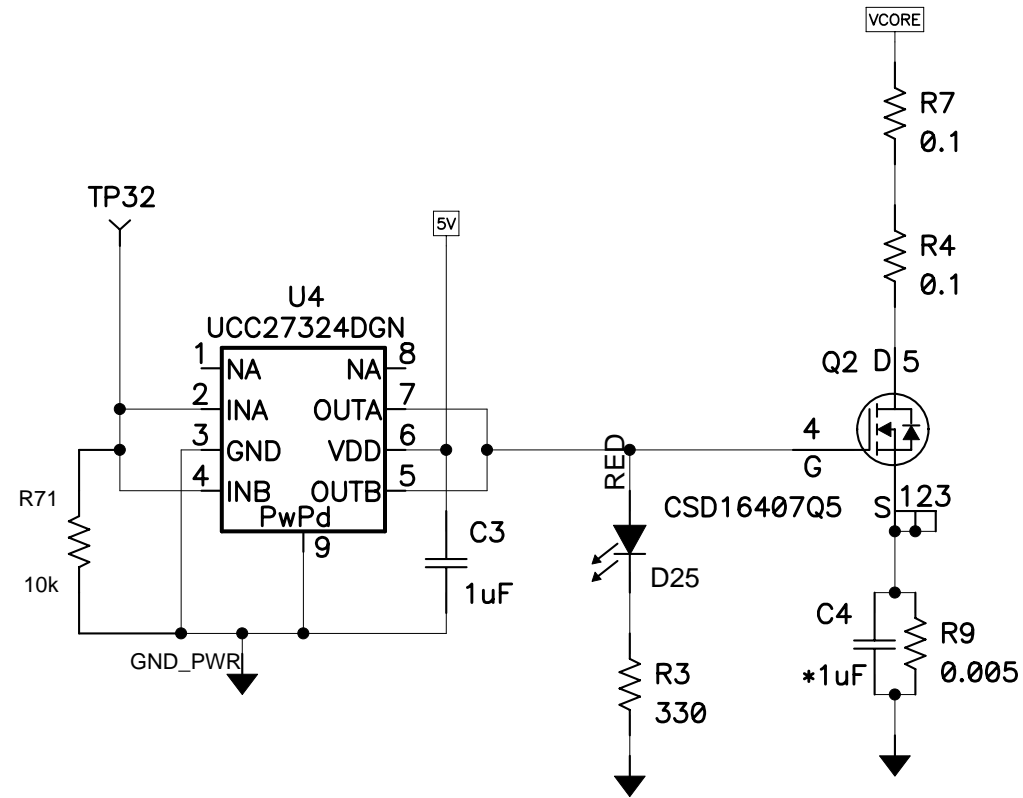
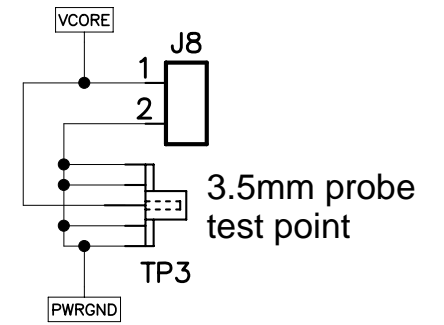
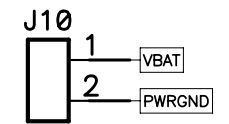
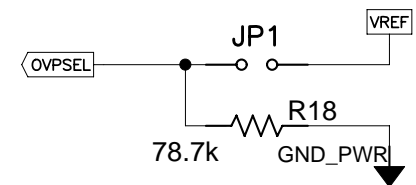
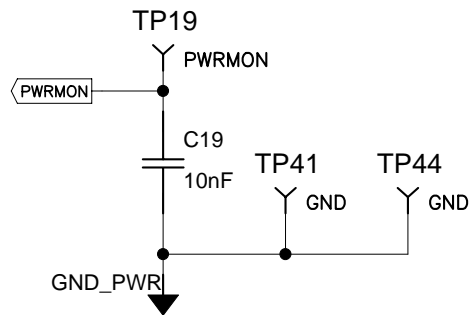


Manual VID Setting
Open = LO

OSRSEL 1 of 4 Selection Header



POWERMON Termination

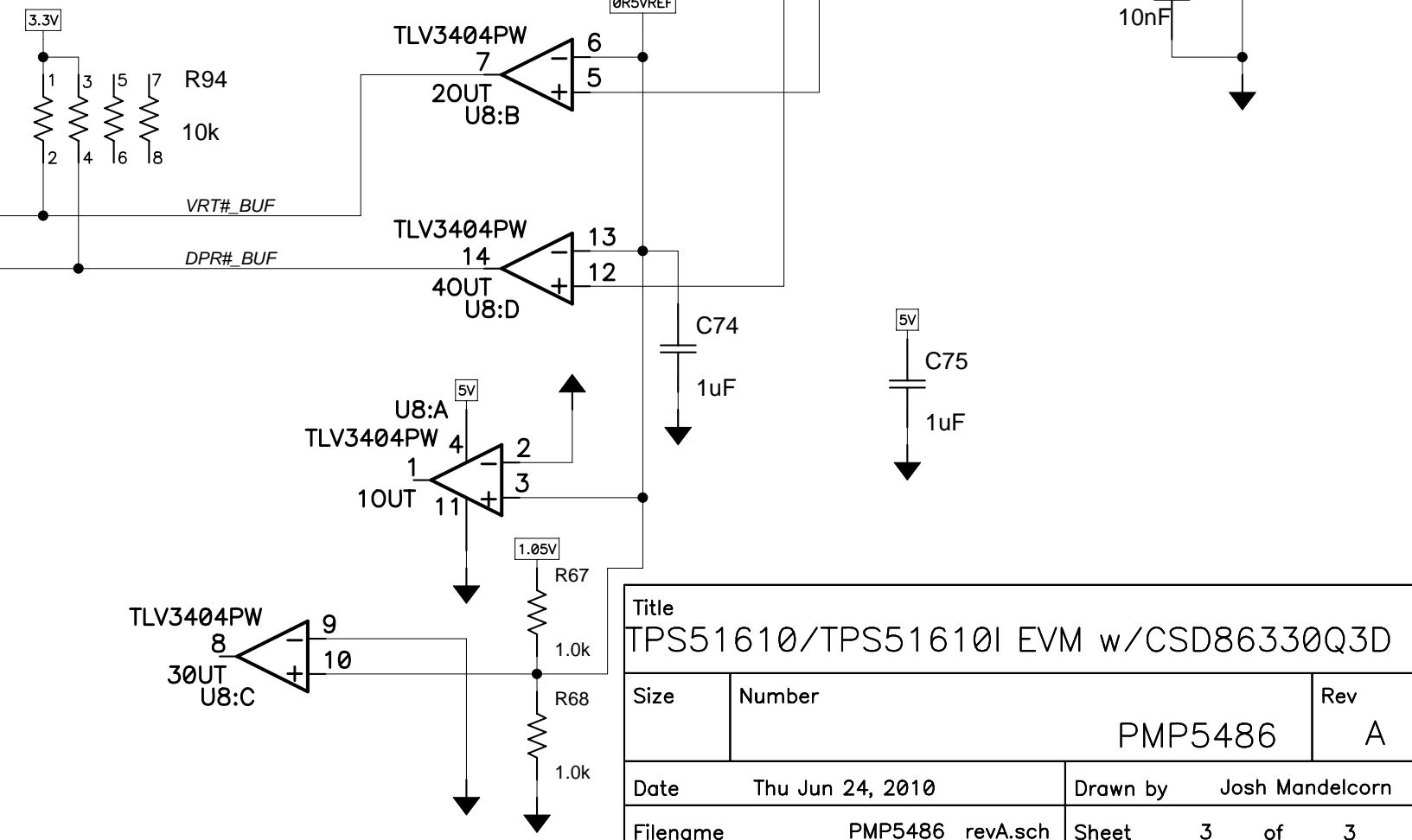
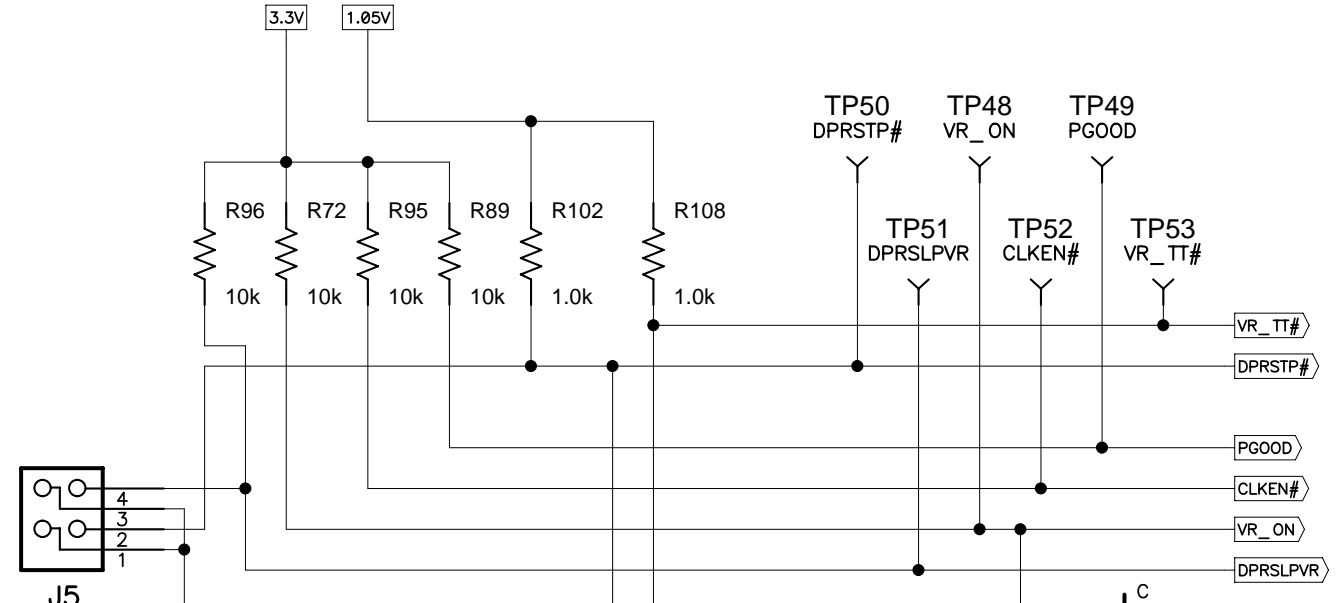
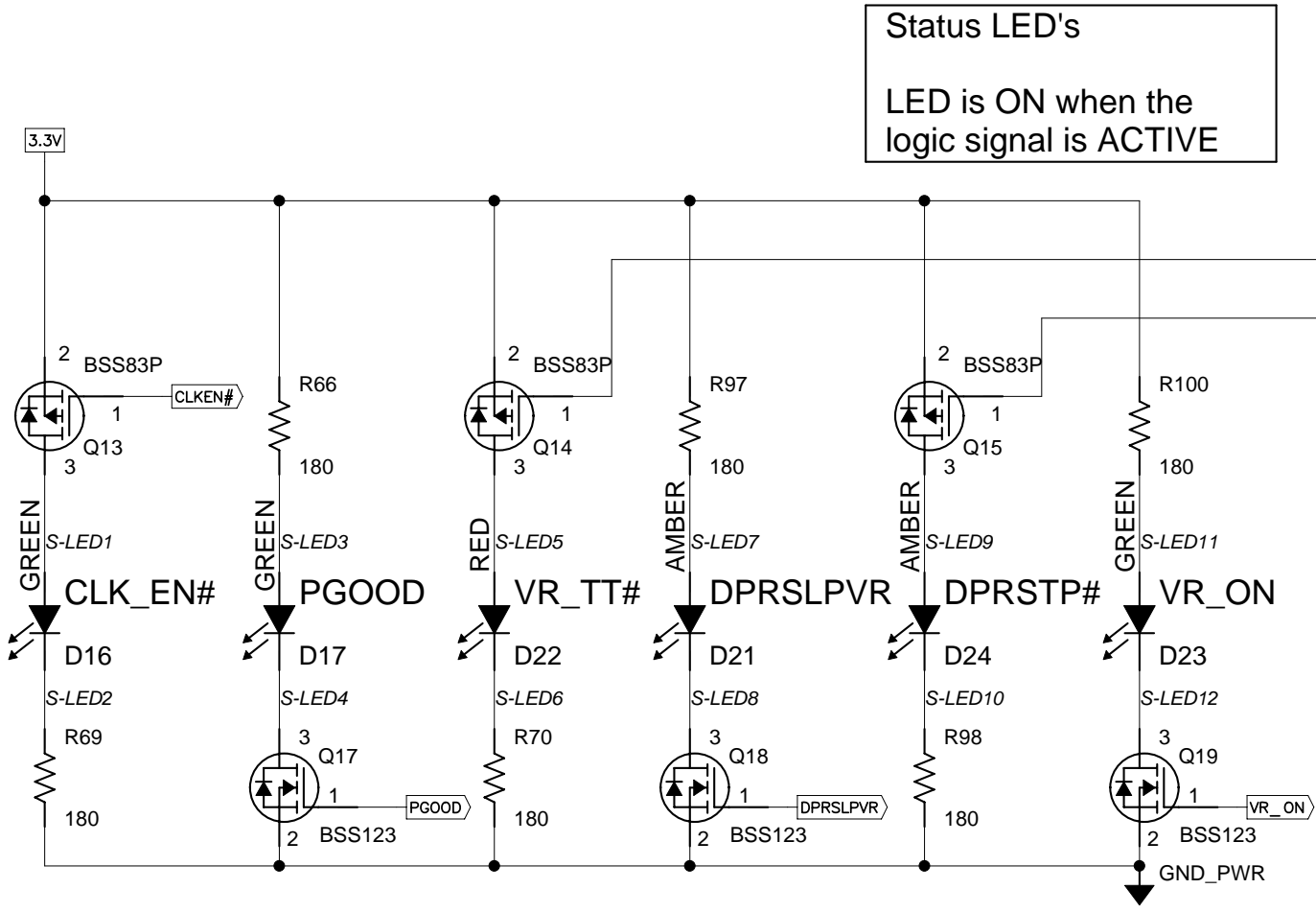
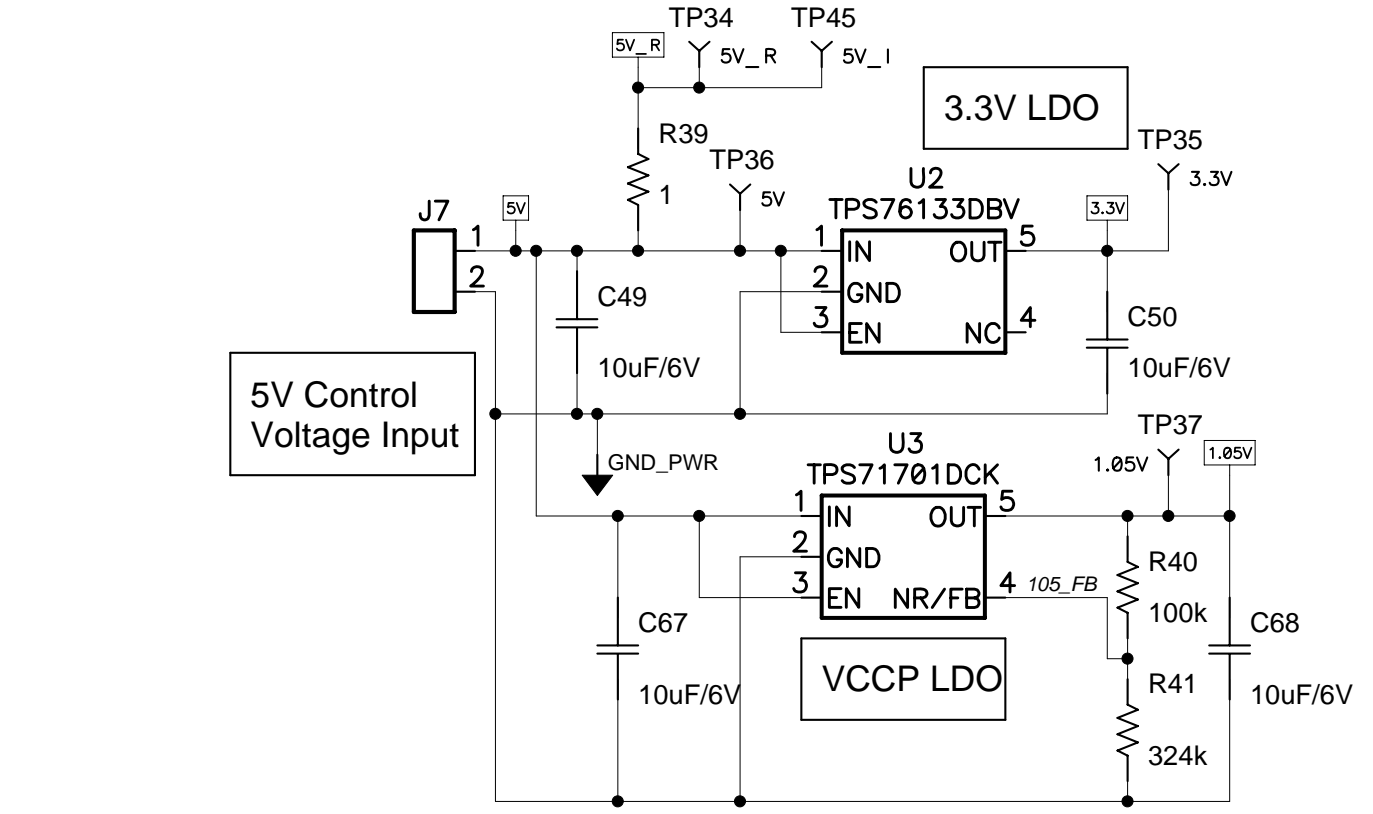


Title		
TPS51610/TPS51610I EVM w/CSD86330Q3D		
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		PMP5486 A
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Logic Signal Termination and Manual Control

5V Control Voltage Input

Status LED's
LED is ON when the logic signal is ACTIVE



Title TPS51610/TPS51610I EVM w/CSD86330Q3D		
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